

ELECTRICALLY INSULATING RESIN COMPOSITION AND METHOD
FOR FORMING THIN FILM THEREFROM

ABSTRACT

An electrically insulating thin-film-forming resin composition comprising (A) an inorganic or organic electrically insulating resin having silicon atom-bonded hydrogen atoms, (B) a compound having groups able to react with the silicon atom-bonded hydrogen atoms in component (A) and having a boiling point under atmospheric pressure of at least 250°C, and (C) a solvent; and a method for forming an electrically insulating thin film therefrom.